

PHYSICAL DIMENSIONS:

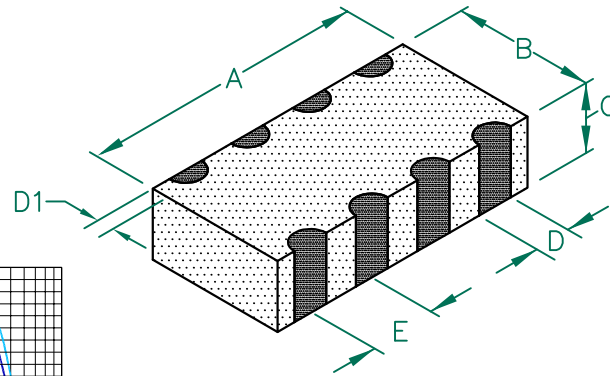
A	3.20 [.126]	± 0.20 [.008]
B	1.60 [.063]	± 0.20 [.008]
C	0.80 [.031]	± 0.20 [.008]
D	0.40 [.016]	± 0.15 [.006]
D1	0.30 [.012]	± 0.20 [.008]
E	0.80 [.031]	± 0.10 [.004]

DA1206B102R-10

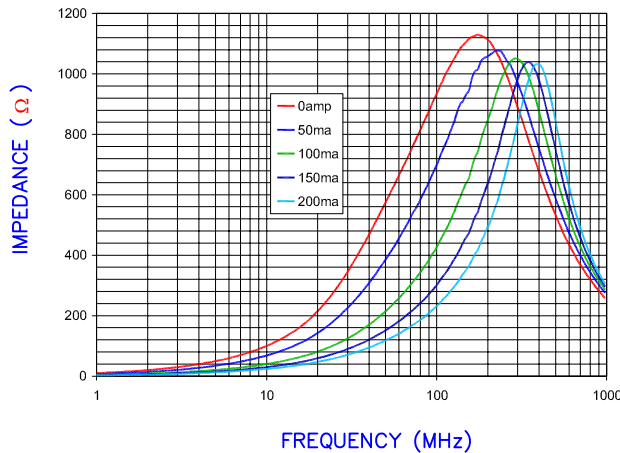
UNCONTROLLED DOCUMENT

ELECTRICAL CHARACTERISTICS:

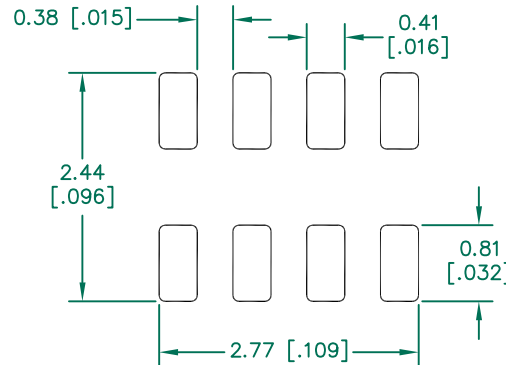
Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	1000	
Minimum	750	
Maximum	1250	0.8
LINE TO LINE INSULATION RESISTANCE >100 M Ω AT 75 VOLTS.		



Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS



LAND PATTERNS FOR REFLOW SOLDERING

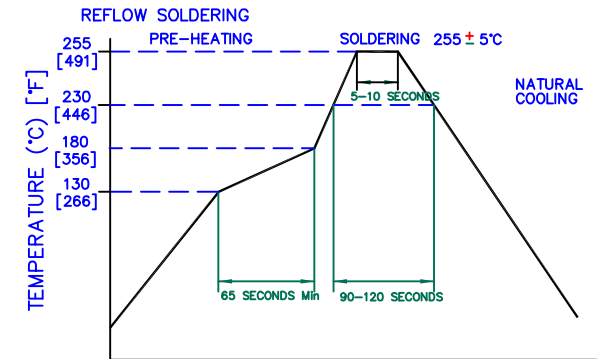


(For wave soldering, add 0.762 (0.030) to this dimension)

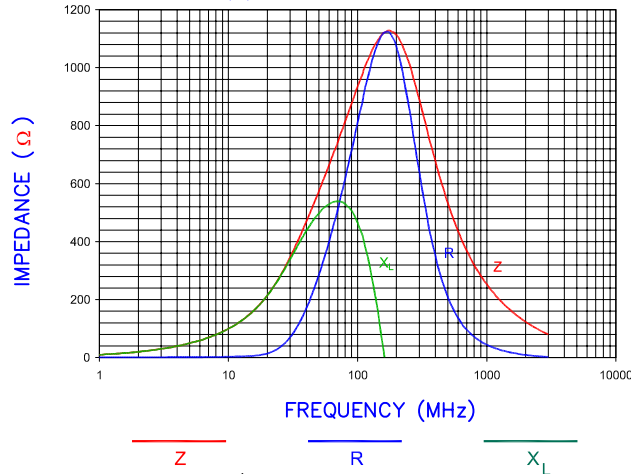
NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL.
2. TERMINATION FINISH IS 100% TIN.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. OPERATING TEMPERATURE TEMP: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$. (INCLUDING SELF-HEATING)

RECOMMENDED SOLDERING CONDITIONS



|Z|, R, AND X vs. FREQUENCY



DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			
F	OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU				
E	CHANGE C DIMENSION	07/29/10	JUN				
D	UPDATE COMPANY LOGO	05/19/09	JRK	PROJECT/PART NUMBER:	REV	PART TYPE:	DRAWN BY:
C	D1 dim chgd from 0.008 ± 0.004 to 0.012 ± 0.008 . UPDATE COMPANY LOGO	10/30/07	JRK	DA1206B102R-10	F	CO-FIRE	TMB
B	CHANGE C DIMS FROM .80 ADD RoHS	09/08/05	JRK	DATE:	SCALE:	SHEET:	
A	ORIGINAL DRAFT	03/29/04	TMB	03/29/04	NTS	2 of 2	
REV	DESCRIPTION	DATE	INT	CAD #	TOOL #		
				DA1206B102R-10-F	-		